

Jakob Schober

List of Publications by Year in descending order

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4
papers

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3311381
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citing authors

| # | ARTICLE | IF | CITATIONS |
|---|---|-----|-----------|
| 1 | Thick Film Photoresist Process for Copper Pillar Bumps on Surface Acoustic Wave - Wafer Level Packages. , 2020, , . | | 5 |
| 2 | Rotate-to-bend setup for fatigue bending tests on inkjet-printed silver lines. Flexible and Printed Electronics, 2018, 3, 035005. | 2.7 | 2 |
| 3 | Reliability Study of Miniaturized Surface Acoustic Wave RF-Filters With Copper Pillar Bump Interconnections. IEEE Access, 2021, 9, 140581-140589. | 4.2 | 1 |
| 4 | Reliability Study of Copper Pillar Bump Interconnects for Acoustic Wave - Wafer Level Package. , 2020, , . | | 0 |